

WHAT IS CLAIMED IS:

1. A method of manufacturing a head suspension assembly comprising:

forming a wiring pattern;

5 mounting a head amplifier IC on the wiring pattern; and

fixing the wiring pattern, mounted with the head amplifier IC, on a suspension and an arm.

10 2. A method of manufacturing a head suspension assembly comprising:

forming a wiring pattern having first and second principal surfaces;

mounting a head amplifier IC on the first principal surface of the wiring pattern;

15 inspecting the mounted head amplifier IC for operation through the wiring pattern;

mounting a slider having a magnetic head on the second principal surface of the wiring pattern after normal operation of the head amplifier IC is confirmed
20 by the inspection; and

fixing the wiring pattern, mounted with the head amplifier IC and the magnetic head, on a suspension and an arm.

25 3. A method of manufacturing a head suspension assembly according to claim 1, wherein said wiring pattern is fixed on the suspension and the arm after the outer surface of the head amplifier IC mounted on

the wiring pattern is coated with a resin.

4. A method of manufacturing a head suspension assembly according to claim 1, wherein said wiring pattern is fitted on the suspension and the arm so
5 that the mounted surface of the head amplifier IC is opposed to the suspension and the arm, and said head amplifier IC is located in an opening formed in the suspension and the arm.

5. A method of manufacturing a head suspension
10 assembly comprising:

forming a wiring pattern sheet having a number of wiring patterns;

mounting a head amplifier IC on each wiring pattern of the wiring pattern sheet;

15 cutting the wiring patterns, mounted with the head amplifier IC each, from the wiring pattern sheet; and

fixing each cut wiring pattern on a suspension and an arm.

20 6. A method of manufacturing a head suspension assembly according to claim 5, wherein each of said wiring patterns is cut from the wiring pattern sheet after the outer surface of the head amplifier IC mounted on the wiring pattern is coated with a resin.

25 7. A method of manufacturing a head suspension assembly according to claim 5, wherein each of said wiring patterns is fitted on the suspension and the

arm so that the mounted surface of the head amplifier IC is opposed to the suspension and the arm, and said head amplifier IC is located in an opening formed in the suspension and the arm.

5 8. A method of manufacturing a head suspension assembly comprising:

 forming a wiring pattern sheet having a number of wiring patterns;

10 mounting a head amplifier IC on a first principal surface of each wiring pattern of the wiring pattern sheet;

 inspecting the mounted head amplifier IC for operation through each wiring pattern;

15 mounting a slider having a magnetic head on a second principal surface of each of those wiring patterns on which the head amplifier IC's concluded to be normal in operation by the inspection are mounted;

20 cutting the wiring patterns, mounted with the slider and the head amplifier IC each, from the wiring pattern sheet; and

 fixing each cut wiring pattern on a suspension and an arm.

25 9. A method of manufacturing a head suspension assembly according to claim 8, wherein each of said wiring patterns is cut from the wiring pattern sheet after the outer surface of the head amplifier IC mounted on the wiring pattern is coated with a resin.

10. A method of manufacturing a head suspension assembly according to claim 8, wherein each of said wiring patterns is fitted on the suspension and the arm so that the mounted surface of the head amplifier IC is opposed to the suspension and the arm, and said head amplifier IC is located in an opening formed in the suspension and the arm.

11. A head suspension assembly comprising:

an arm;

a suspension extending from the arm and having a proximal end portion fixed to the arm;

a wiring pattern provided on the arm and the suspension;

a head amplifier IC mounted on a first principal surface of the wiring pattern; and

a slider mounted on a second principal surface of the wiring pattern and fitted with a magnetic head,

the respective proximal end portions of the arm and the suspension having a opening penetrating the arm and the suspension,

the wiring pattern being fitted on the suspension and the arm in a manner such that the first principal surface is opposed to the arm and the suspension, and the head amplifier IC being located in the opening.

12. A head suspension assembly according to claim 11, wherein said head amplifier IC is formed of

a bare chip, and the outer surface of said head amplifier IC is coated with a resin.